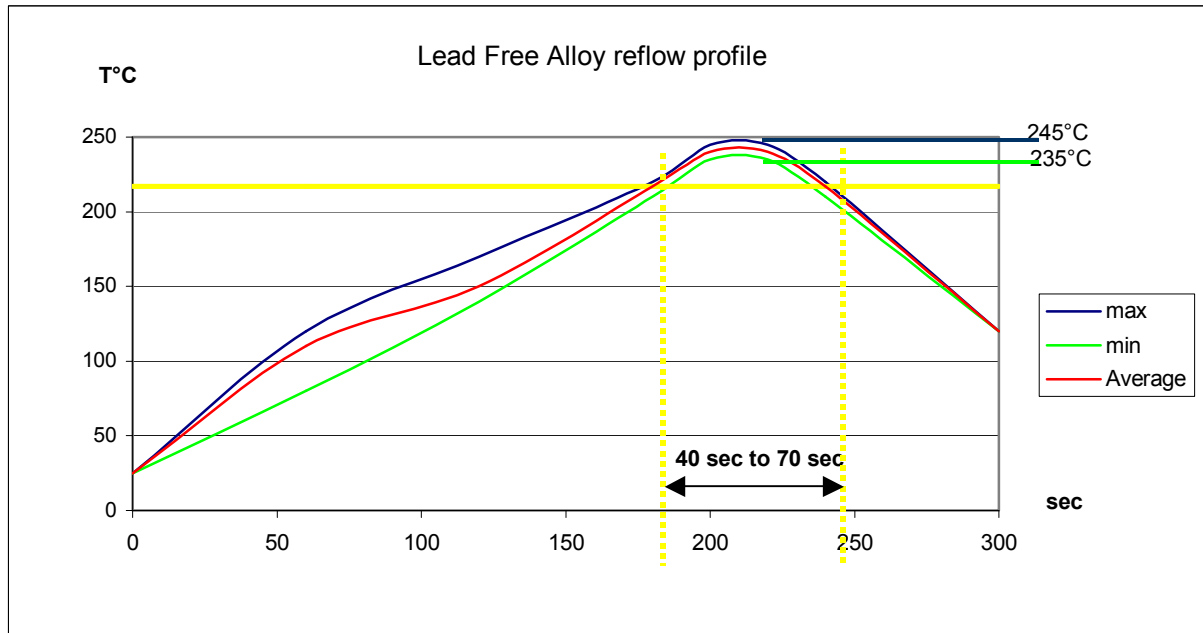




TYPICAL REFLOW PROFILE 1

Sn95.5Ag3.8Cu0.7 Lead Free Alloy



Typical reflow profile of solder pads across a SMT assembly using the Sn95.5Ag3.8Cu0.7 Lead Free Alloy

Reflow system was a Hot Air Convection reflow oven